

## P-Channel Enhancement-Mode Vertical DMOS FET

#### **Features**

- ▶ Free from secondary breakdown
- Low power drive requirement
- Ease of paralleling
- Low C<sub>iss</sub> and fast switching speeds
- High input impedance and high gain
- Excellent thermal stability
- ► Integral source-to-drain diode

### **Applications**

- Motor controls
- Converters
- Amplifiers
- Switches
- Power supply circuits
- Drivers (relays, hammers, solenoids, lamps, memories, displays, bipolar transistors, etc.)

#### **General Description**

The Supertex VP2206 is an enhancement-mode (normally-off) transistor that utilizes a vertical DMOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors, and the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, this device is free from thermal runaway and thermally-induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where very low threshold voltage, high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

### **Ordering Information**

Device	Packaç	e Options	BV <sub>pss</sub> /BV <sub>pgs</sub>	DSS DGS	
Device	TO-39	TO-92	(V)	(max) (Ω)	(min) (A)
VP2206	VP2206N2 <sup>†</sup>	VP2206N3-G	-60	0.9	-4.0

<sup>-</sup>G indicates package is RoHS compliant ('Green')† package is RoHS compliant ('Green')





### **Absolute Maximum Ratings**

Parameter	Value
Drain-to-source voltage	$BV_{DSS}$
Drain-to-gate voltage	$BV_{DGS}$
Gate-to-source voltage	±20V
Operating and storage temperature	-55°C to +150°C
Soldering temperature*	300°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

### **Pin Configuration**



#### **Product Marking**



Package may or may not include the following marks: Si or

TO-39 (N2)

SiVP 2206 YYWW

YY = Year Sealed WW = Week Sealed \_\_\_\_\_ = "Green" Packaging

Package may or may not include the following marks: Si or \$\mathbb{H}\$

TO-92 (N3)

<sup>\*</sup> Distance of 1.6mm from case for 10 seconds.

#### **Thermal Characteristics**

Package	Package $I_D$ $I_D$ $I_D$ (pulsed) (A) (A)		Power Dissipation @T <sub>c</sub> = 25°C (W)	θ <sub>JC</sub> (°C/W)	θ <sub>JA</sub> (°C/W)	t   DR (A)	I <sub>DRM</sub> (A)
TO-39	-0.75	-8.0	6.0	20.8	125	-0.75	-8.0
TO-92	-0.64	-4.0	1.0	125	170	-0.64	-4.0

Notes:

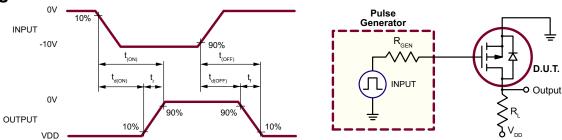
## Electrical Characteristics (T<sub>A</sub> = 25°C unless otherwise specified)

Sym	Parameter	Min	Тур	Max	Units	Conditions
BV <sub>DSS</sub>	Drain-to-source breakdown voltage	-60	-	-	V	$V_{GS} = 0V$ , $I_D = -10mA$
$V_{\rm GS(th)}$	Gate threshold voltage	-1.0	-	-3.5	V	$V_{GS} = V_{DS}$ , $I_{D} = -10$ mA
$\Delta V_{\text{GS(th)}}$	Change in V <sub>GS(th)</sub> with temperature	-	-4.3	-5.5	mV/°C	$V_{GS} = V_{DS}$ , $I_{D} = -10$ mA
I <sub>GSS</sub>	Gate body leakage	-	-1.0	-100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
			-	-50	μA	$V_{GS} = 0V, V_{DS} = Max Rating$
I <sub>DSS</sub>	Zero gate voltage drain current	-	-	-10	mA	$V_{DS} = 0.8$ Max Rating, $V_{GS} = 0V$ , $T_A = 125$ °C
	On state drain surrent	-0.85	-2.0	-		$V_{GS} = -5.0V, V_{DS} = -25V$
D(ON)	On-state drain current	-4.0	-9.0	-	Α	V <sub>GS</sub> = -10V, V <sub>DS</sub> = -25V
В	Static drain to course an etate registeres	-	1.3	1.5	Ω	V <sub>GS</sub> = -5.0V, I <sub>D</sub> = -1.0A
R <sub>DS(ON)</sub>	Static drain-to-source on-state resistance	-	0.75	0.9	1 12	$V_{GS} = -10V, I_{D} = -3.5A$
$\Delta R_{DS(ON)}$	Change in R <sub>DS(ON)</sub> with temperature	-	0.85	1.2	%/°C	$V_{GS} = -10V, I_{D} = -3.5A$
G <sub>FS</sub>	Forward transductance	800	1400	-	mmho	$V_{DS} = -25V, I_{D} = -2.0A$
C <sub>ISS</sub>	Input capacitance	-	325	450		V <sub>GS</sub> = 0V,
C <sub>oss</sub>	Common source output capacitance	-	125	180	pF	$V_{DS} = -25V$ ,
C <sub>RSS</sub>	Reverse transfer capacitance	-	30	40		f = 1.0MHz
t <sub>d(ON)</sub>	Turn-on delay time	-	4.0	15		
t <sub>r</sub>	Rise time Turn-off delay time		16	25	ns	$V_{DD} = -25V,$ $I_{D} = -4.0A,$
t <sub>d(OFF)</sub>			16	50		$R_{GEN} = 10\Omega$
t <sub>f</sub>	Fall time	-	22	50		GEN
V <sub>SD</sub>	Diode forward voltage drop	-	-1.1	-1.6	V	$V_{GS} = 0V, I_{SD} = -3.5A$
t <sub>rr</sub>	Reverse recovery time	-	500	-	ns	$V_{GS} = 0V, I_{SD} = -1.0A$

#### Notes:

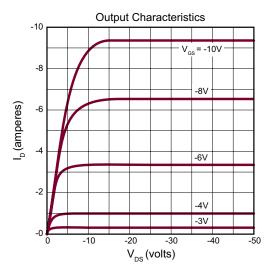
- 1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300µs pulse, 2% duty cycle.)
- 2. All A.C. parameters sample tested.

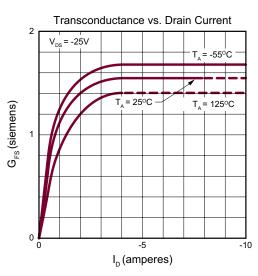
### **Switching Waveforms and Test Circuit**

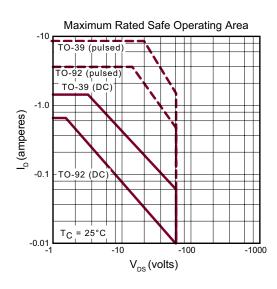


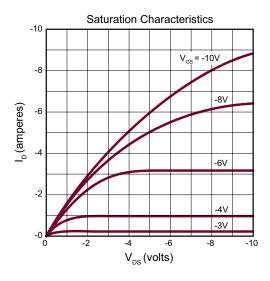
 $<sup>\</sup>dagger$  I<sub>D</sub> (continuous) is limited by max rated T<sub>J</sub>.

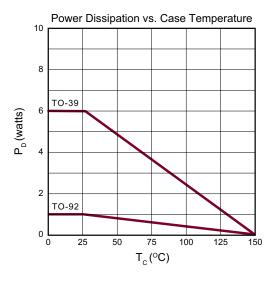
### **Typical Performance Curves**

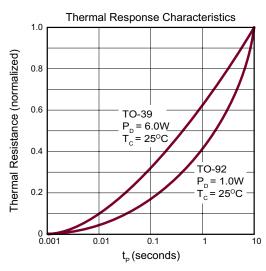




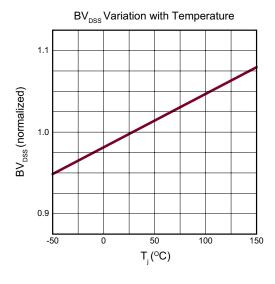


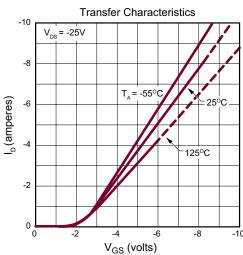


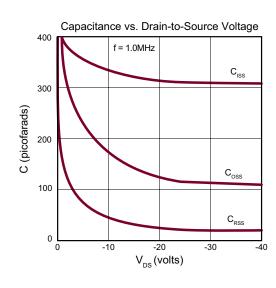


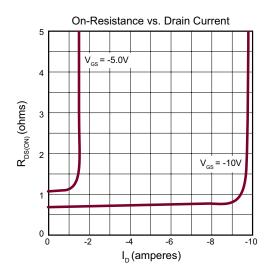


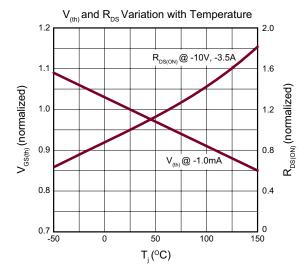
### **Typical Performance Curves** (cont.)

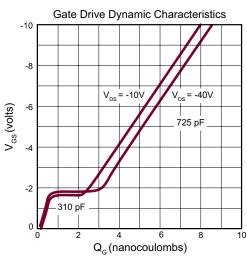




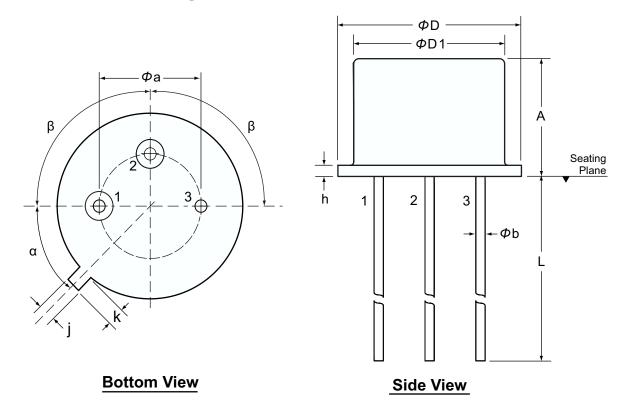








# 3-Lead TO-39 Package Outline (N2)



Symbol		α	β	Α	Фа	<b>Φ</b> b	ΦD	<b>Φ</b> D1	h	j	k	L
Dimension (inches)	MIN		.240	.190	.016	.350	.315	.009	.028	.029	.500	
	NOM	45° NOM	90° NOM	-	-	-	-	-	-	-	-	-
	MAX			.260	.210	.021	.370	.335	.125	.034	.040	.560*

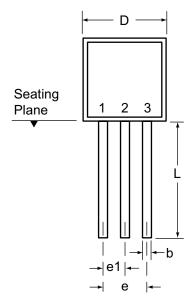
Drawings not to scale.

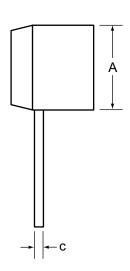
Supertex Doc. #: DSPD-3TO39N2, Version B052009.

JEDEC Registration TO-39.

\* This dimension is not specified in the JEDEC drawing.

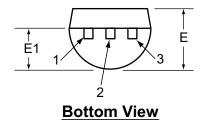
## 3-Lead TO-92 Package Outline (N3)





**Front View** 

**Side View** 



Symbol		Α	b	С	D	E	E1	е	e1	L
Dimensions (inches)	MIN	.170	.014 <sup>†</sup>	.014 <sup>†</sup>	.175	.125	.080	.095	.045	.500
	NOM	-	-	-	-	-	-	-	-	-
	MAX	.210	.022 <sup>†</sup>	.022 <sup>†</sup>	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92.

Drawings not to scale.

Supertex Doc.#: DSPD-3TO92N3, Version E041009.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <a href="http://www.supertex.com/packaging.html">http://www.supertex.com/packaging.html</a>.)

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<sup>\*</sup> This dimension is not specified in the JEDEC drawing.

<sup>†</sup> This dimension differs from the JEDEC drawing.